	12/19/2012		PMP8871 REVB BOM			
Qty	Ref Des	Value	Description	Size	Part Number	Manuf
1	C13	0.039uF	Capacitor, Ceramic, 50V, X7R, 10%	603	Std	TDK
	C4 C5 C9 C12					
6	C15 C17	0.1uF	Capacitor, Ceramic, 50V, X7R, 10%	603	Std	TDK
1	C18	1.0uF	Capacitor, Ceramic, 16V, X7R, 20%	603	Std	TDK
1	C10	330pF	Capacitor, Ceramic, 50V, X7R, 10%	603	Std	TDK
3	C2-3 C6	47uF	Capacitor, Ceramic, 10V, X5R, 10%	1210	C3225X5R1A476M	TDK
1	C11	1000pF	Capacitor, Ceramic, 250Vac, X1 Y1	8mm	DE1E3KX102MA5BA01	Murata
1	C8	330uF	Capacitor, POSCAP, 0.025 ohms, 3Arms, 10V	D4	10TPE330M	Sanyo
1	D1	MBRS340T3G	Diode, Schottky, 3A, 40V	SMC	MBRS340T3G	On Semi
1	D2	B140	Diode, UltraFast Rectifier, 1A, 40V	SMA	B140	Diodes Inc
1	D3	BAT54STA	Diode, Dual Schottky, 200-mA, 30-V	SOT23	BAT54STA	Zetex
2	J1-2	ED555/2DS	Terminal Block, 2-pin, 6-A, 3.5mm	0.27" x 0.25"	ED555/2DS	OST
3	J3-5	PEC02SAAN	Header, Male 2-pin, 100mil spacing,	0.1" x 2	PEC02SAAN	Sullins
1	JP1	PEC03SAAN	Header, Male 3-pin, 100mil spacing	0.1" x 3	PEC03SAAN	Sullins
2	R2 R12	0	Resistor, Chip, 1/16W, 1%	603	Std	Std
1	R5	6.8	Resistor, Chip, 1/16W, 1%	603	Std	Std
2	R3 R4	49.9	Resistor, Chip, 1/16W, 1%	603	Std	Std
1	R9	499	Resistor, Chip, 1/16W, 1%	603	Std	Std
1	R13	1.47k	Resistor, Chip, 1/16W, 1%	603	Std	Std
2	R14 R100	10k	Resistor, Chip, 1/16W, 1%	603	Std	Std
1	R10	196k	Resistor, Chip, 1/16W, 1%	603	Std	Std
1	R8	30.1k	Resistor, Chip, 1/16W, 1%	603	Std	Std
2	R6-7	4.99k	Resistor, Chip, 1/16W, 1%	603	Std	Std
1	R1	301	Resistor, Thick Film, 1/10 watt, ± 5%	805	Std	Std
1	T1	7.5uH	XFMR, 7.5uH, 1:2 Turns Ratio	21.45x15.7mm	RLTI-1076	Renco
6		5000	Test Point, Red, Thru Hole Color Keyed	0.1 x 0.1"	5000	Keystone
2	TP3-4	5001	Test Point, Black, Thru Hole Color Keyed	0.1 x 0.1"	5001	Keystone
1	U1		IC, 5-A High Voltage Boost Converter	QFN-16	TPS55340RTE	TI
1	U3	TLV431CDBZR	IC, Low-Voltage Adjustable Shunt Regulator	SOT23-3	TLV431CDBZR	TI
1	U4	FOD817ASD	IC, Optocoupler, 5KV, 80%-160% CTR	SMT-4PDIP	FOD817ASD	Fairchild
2	C14 C16	open	Capacitor, Ceramic	603	Std	TDK
1	C7	open	Capacitor, Ceramic, 10V, X5R, 10%	1210	C3225X5R1A476M	TDK
1	C1	open	Capacitor	Multi sizes		
1	R11	open	Resistor, Chip, 1/16W, 1%	603	Std	Std

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